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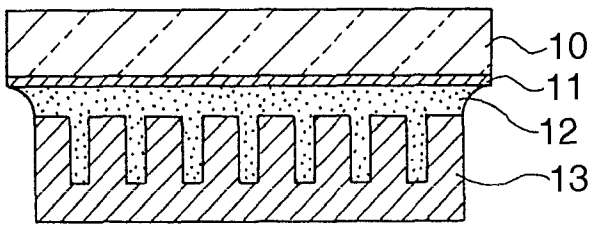
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(54) **Title:** METHOD OF PRODUCING SEGMENTED CHIPS



(57) **Abstract:** To provide a method of producing segmented chips preventing the chips from being damaged by the chip jumping or by the contact of the neighboring chips while the back surfaces thereof are being ground. A method of producing segmented chips by grinding the back surface of a material to be ground which includes a plurality of chips segmented into individual chips by at least partly cutting the chips in the direction of thickness thereof along the boundaries of the chips, wherein the gaps among the individual chips are filled with a liquid adhesive, the material to be ground is laminated on a rigid support material in a manner that the back surface thereof is exposed, and the adhesive is cured or solidified to form a laminate of the material to be ground having the plurality of chips, the adhesive solid material and the rigid support material arranged in this order; the laminate is ground from the back surface side of the material to be ground, the rigid support member is removed from the laminate, a flexible adhesive sheet is adhered onto the adhesive solid material, and the individual chips are picked up and recovered.

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